

ELECTRIC LOAD MANAGEMENT CENTER

RELATED APPLICATION

[0001] This application claims priority under 35 U.S.C. §119(e) of U.S. Provisional Application No. 60/267,520 filed on February 8, 2001, the entire contents of which are herein incorporated by reference.

FIELD OF THE INVENTION

[0002] The present invention relates to electric power distribution and vehicle power management systems for vehicles having multiple separately controlled electrical loads.

BACKGROUND OF THE INVENTION

[0003] Electrical power controllers have been used for the distribution of electrical power on aircraft and other vehicles. Additionally, modular approaches to supplying vehicle power have been used to facilitate both maintenance and operability under fault conditions.

[0004] New generation vehicles have significantly different electric power requirements. For example, in aerospace systems, there has been a fundamental paradigm shift from predominantly mechanical or electromechanical control to predominantly electronic and computer-based control, with no or minimal backup. This shift toward fly-by-wire systems has been pioneered in Europe by Airbus and now encompasses safety-critical systems.

[0005] This shift in technology poses fundamental technical and commercial challenges, which require advanced power distribution controllers such as an Electric Load management Center (ELMC). Advances in switching technology (solid state) and computer control now offer the potential for fully automated electric power systems (EPS). A combination of solid state power controllers (SSPC), remote power controllers, smart contactors, and automatic system processors has evolved into ELMC.

[0006] As computer-controlled system technology advances more system functions, including power control, fall under computer-controlled command. A more advanced technology in the power control and protection is making its way into aerospace power systems to replace mechanical circuit breakers and relays.

[0007] United States Patent No. 5,752,047 issued to Darty et al. discloses a modular solid state power controller with microcontrollers. The modular solid state power controller includes low cost low speed microcomputers embedded within the load cards to control a number of semiconductor power switches associated with corresponding electrical load circuits. A master controller microcomputer on the controller card communicates bilaterally with each of the microcomputers embedded within the load cards via a serial data path that extends along the backplane card and interconnects the controller microcomputer with each of the load cards. Each of the load cards includes semiconductor power switches associated with the respective slave card, which are activated upon commands issued from the controller microcomputer.

[0008] However, the Darty et al. design utilizes discrete components to provide limited control of the power switches. Therefore, this modular solid state power controller with microcomputers is limited to basic on/off control of the power switches and does not permit local control functionality and flexible configuration of the SSPCs.

[0009] Therefore, it is desired to have an ELMC that includes integrated advanced power switch controllers that interface with the local microcontrollers and allow for additional control and configuration of each individual power switch.

SUMMARY OF THE INVENTION

[0010] In accordance with the present invention, the deficiencies in prior systems are overcome by providing an electrical power distribution center comprising: a gateway module including logic to interface to a vehicle management computer (VMC) via a dual redundant standard data

bus. The gateway module comprises redundant microcontrollers operably connected to the VMC for selectively controlling the supply of electrical power to a plurality of separate electrical loads. The electrical power distribution center also has two internal serial data buses. The two
5 internal serial data buses are of two different types and the redundant microcontrollers are each operably connected to the two internal serial data buses. A plurality of Load Management Modules (LMMs) is also provided. Each Load Management Module is operably connected to the internal serial data buses for receiving control commands from the
10 gateway module. Each Load Management Module comprises a local microcontroller; a plurality of power switching devices; and a plurality of application specific integrated circuits (ASICs) corresponding to the plurality of power switching devices for interfacing the power switching devices to the local microcontroller.

15 [0011] Further scope of applicability of the present invention will become apparent from the detailed description provided hereinafter. However, it should be understood that the detailed description and specific embodiments, while disclosing the preferred embodiments of the invention, are provided by way of illustration only. Those skilled in the art
20 will appreciate that various changes and modifications are within the spirit and scope of the invention and will become apparent from the detailed description that follows.

BRIEF DESCRIPTION OF THE DRAWINGS

25 [0012] A more complete understanding of the present invention will become apparent from the following description taken in conjunction with the accompanying drawings, wherein:

Fig. 1 illustrates a modular architecture in accordance with an aspect of the present invention;

30 Fig. 2 illustrates a block diagram of the ELMC communication with the vehicle in accordance with an aspect of the present invention;

Fig. 3A illustrates a block diagram of a Load Management Module in accordance with an aspect of the present invention;

Fig. 3B illustrates a block diagram of logic in an application specific integrated circuit in accordance with an aspect of the present invention;
5 and

Fig. 4 illustrates packaging of the ELMC in accordance with an aspect of the present invention.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

10 [0013] Aspects of the invention are disclosed in the following description. Those skilled in the art will appreciate that alternate embodiments can be devised without departing from the spirit or the scope of the invention.

15 [0014] The Electrical Load Management Center (ELMC) is responsible for the distribution of electrical power to the vehicle. It also can supply control logic for some vehicle systems. Thus, the ELMC replaces complex relay logic and circuit cards that are part of the traditional subsystems control. Additionally, the ELMC can provide status information to an electrical power system display to provide a real time picture of the electrical power system configuration.

20 [0015] By reducing system complexity and increasing system functionality, the ELMC provides lower system weight, higher reliability, higher system availability, better maintainability and lower cost of ownership to the end user.

25 [0016] As mentioned above, modern vehicles have significantly different electric power requirements. These requirements include remote control / interfacing with vehicle management computers, increased reliability, fault tolerance (e.g., to cover for powered-by- wires or fly-by-wires implementations and features), increased electrical power demands and reduced direct maintenance cost (DMC).

30 [0017] The ELMC incorporates control, protection, and built-in test (BIT) functions for improved availability and maintainability. The ELMC

can interface with a higher-level management computer for command control and status reporting. The power and control hardware are carefully designed for compatibility into current vehicle (e.g., aircraft) systems such that it provides the power flow and status data while optimizing size, weight, and efficiency constraints.

[0018] Additionally, the ELMC in accordance with the present inventions has various fault detection and isolation functions. The ELMC has the ability to test, monitor and report on system (e.g., electric power) health and to individually identify failed solid state switching devices (SSSDs) in specific LMMs to minimize maintenance efforts on the entire vehicle.

[0019] Another aspect of the present invention is the ELMC configured as a Line Replaceable Unit (LRU) used in the distribution of electrical power for airborne, seaborne, land or space vehicles. In this context, the term distribution includes but is not limited to the switching of power from various power buses within the ELMC, the protection of wiring downstream of the power switching devices, the reporting back of the status of the power switching devices, and provision of load management functions such as load shedding, sequencing of load switching, and the like.

[0020] The above-mentioned ELMC is built on a modular architecture concept for flexibility. The ELMC contains LMMs and other circuit cards to provide conditioned power supply, analog and digital signal conditioning and interfacing with the host vehicle through a gateway module and associated controller.

[0021] A LMM is a circuit card assembly that contains a plurality of solid state switching devices / power switching devices. The LMM is used to switch AC or DC power, protect the wiring from overcurrent conditions and distribute the power to utilization equipment. The LMM can replace hybrid solid state power controllers or the combination of relay and circuit breakers. The SSSD and LMM are modular in design

itself so that each can be applied to many applications. A microcontroller, also located on the LMM, interfaces the SSSDs with the gateway module. Each SSSD includes a mixed technology Application Specific Integrated Circuit (ASIC) that controls switch drivers, monitoring and overcurrent protection functions, and the like. Each power switching device (PSD), installed on the LMM provides line power switching and is controlled by an ASIC.

[0022] An exemplary embodiment of a modular architecture according to the present invention is shown in Fig. 1. A gateway module 100 including logic 112 to interface to a vehicle management computer (VMC) 50 via a dual redundant standard data bus 1. The term "logic" as used herein refers to any combination of hardware, software and or combinations of hardware and software to implement the associated function, as will be appreciated by those skilled in the art. The gateway module 100 comprises redundant microcontrollers 114, 116 operably connected to the VMC 50 for selectively controlling supply of electrical power to a plurality of separate electrical loads 120. The communication with the VMC 50 is implemented by any suitable serial communication such as ARINC 429, ARINC 629, MIL-STD-1 553, Avionics Full Duplex Switch Ethernet (AFDSE), and the like. In the modular design of present invention, only the gateway module 100 is modified to accommodate a new communication protocol.

[0023] Within the ELMC, two types of serial data buses 2, 3 are used for intra-ELMC communication. The redundant microcontrollers 114, 116 are each operably connected to the two internal serial control buses 2, 3. In this example, the two internal serial data buses are Synchronous Serial Peripheral Interface (SPI) and Asynchronous Serial Communications Interface (SCI), which were chosen for dissimilarity purposes. The SPI is a high-speed communication, full-duplex, three-wire synchronous transfer bus. The SCI is a serial UART type asynchronous communication bus, full-duplex, single wire operation mode. As the ELMC motherboard is the

critical common link between gateway module and LMMs, the two communication buses provide dual redundancy and reduce occurrence rate of a common mode failure. Dissimilar control and communication techniques are used in critical systems to reduce common mode failures.

5 For example, an undetected software error (e.g., virus, bug and the like) will affect one system but not be replicated by or affect the other.

[0024] External discrete and analog input signals 4 can be fed to the gateway module 100 and LMMs 300 for subsystem control. A plurality of LMMs 300 including local microcontroller 310 is shown. Each Load
10 Management Module 300 is operably connected to the internal serial data buses 2, 3 for receiving control commands via the gateway module 100.

[0025] Referring to Fig. 2, a block diagram of the gateway module is shown. Critical components are replicated to achieve fault tolerance, such as the microcontroller having a dual-redundant channel. The
15 gateway module 100 contains one low cost microcontroller 114, 116 per channel interfaced to the data bus remote terminal interfaces 214, 216, respectively. These communicate with microcontrollers 114, 116 via an internal control bus 230. Redundant control logic 240 provides supervisory control and decides which of the channels (both are
20 simultaneously active) are in control at any particular time. Those skilled in the art will appreciate that the gateway module 100 is interconnected such that either microcontrollers 114, 116, can communicate with the VMC 50 via the redundant data bus 1 and the LMMs 300 using either of the internal serial data buses 2, 3. Thus, a failure of any one of these
25 components does not prevent operation of the ELMC.

[0026] A block diagram of a Load Management Module 300 is shown in Fig. 3A. Each Load Management Module includes a local microcontroller 310, a plurality of power switching devices 320, and a plurality of application specific integrated circuits (ASICs) 330
30 corresponding to the plurality of power switching devices for interfacing the power switching devices 320 to the local microcontroller 310.

[0027] The LMMs are packaged in a manner that minimizes cost and thermal dissipation when compared to conventional devices. At the LMM level, the local monitoring is based on channel tracing. One advantage of this approach is that the system behavior can be observed without
5 intrusion. Those skilled in the art will appreciate that this approach requires additional software that observes application tasks during runtime and traces task states, discrete values, and the like.

[0028] To achieve a higher level of integration, these features and associated circuits are incorporated in a mixed technology ASIC 330, as
10 shown in Fig. 3B. The ASIC 330 incorporates and packages load switching and protective functions. These functions are enabled by related "logic", which as noted above refers to any combination of hardware, software and or combinations of hardware and software to implement the associated function, as will be appreciated by those skilled
15 in the art. It covers both AC and DC modes and applications with various current ratings. Mode selection is accomplished by connecting a mode select pin 331 to a corresponding logic level. For example, the default mode (not connected) is AC.

[0029] Power up reset logic 332 executes an internal reset and
20 calibration cycle during a power-up sequence, to increase the accuracy over temperature and aging ranges. Examples of additional functions/circuits of the ASIC 330 include: gate driver 333 for providing a gating on of the PSD in response to a command signal; providing I^2t characteristics 334; fast shut down (i.e., instant trip function) 335;
25 providing real time status of the power switching device; and tailoring of power switching functions to control or limit the rate of change of the current during switching (e.g., soft turn on off for DC and zero voltage crossing turn on / zero crossing current turn off for AC).

[0030] Each ASIC 330 also includes an analog signal processing
30 block 338 that conditions a load current sense voltage across the shunt resistor 322 to produce a true RMS current value via RMS value

calculation logic 337. Those skilled in the art will appreciate that a true RMS current is not a trivial value to obtain, especially in switched power systems where the DC current is not pure DC current and the AC current is not purely sinusoidal containing only one frequency. However, the true

5 RMS current is critical for calculating RMS heating and I^2t values related to thermal limits of protected components and protected wiring. For example, each ASIC includes an analog processor 334 that uses the I^2t value to control variable trip times (i.e., removing power from the down stream devices) under different application configurations (e.g.

10 overcurrent for a calculated period of time based on I^2t formula)

[0031] As described above, each ASIC includes zero-crossing current processing/detection 339 and zero-crossing voltage processing/detection 341. Zero-crossing voltage detection is done in a centralized location (e.g. power supply module). It represents a square

15 waveform, in phase with the AC line voltage (so it follows the period and phase of the AC line voltage – constant or variable frequency). The zero-crossing current processing/detection 339 and zero-crossing voltage processing/detection 341 are used for controlling on/off activation and respective deactivation timing of the corresponding power switching

20 device when operating in an AC mode. Those skilled in the art will appreciate that a soft-start function is used when operating in a DC mode. The soft start can be a simple ramp function, log function, S-function and the like as is well known in the art.

[0032] Further, unlike prior designs, the design of the ELMC allows

25 individual ASICs 330 to be coordinated thereby allowing ganged operation. As illustrated in Fig. 3A, the LMM 310 has a plurality (e.g., eight as shown) of power switching devices 320 and corresponding ASICs 330. For example, three ASICs 330 can be gang operated in an AC mode to control a three-phase power source. Prior systems, such as

30 the previously mentioned United States Patent No. 5,752,047, have no practical way to control multi-phase loads in a coordinated manner.

[0033] The local microcontroller 310 is isolated from the ASIC's 330 high voltage side driver and power lines using optocouplers 340.

Redundant power supplies, 342, 344 energize the individual ASIC channels and preserve isolation. The redundant power supplies 342, 344 are isolated low power DC to DC converters that supply power to the ASICs 330. DC to DC converters are well know in the art and will not be described further herein.

[0034] PSDs 320 can use hermetic components and packaging for extreme environmental conditions or can use plastic packages for commercial applications. The PSDs 320 uses power MOSFET technology to minimize power dissipation from the power switching devices and provide both AC and DC capabilities. Each PSD contains at least one transistor/ switching device (not shown), a sense resistor (shunt) 322 and a temperature sensor 324. Each ASIC 330 includes a thermal shut-down circuit 336, as shown in Fig. 3B, that opens the corresponding power switching device when the substrate of the power switching device exceeds a predetermined reference temperature, as detected by temperature sensor 324. The predetermined reference temperature can be adjusted using an external setting resistor (not shown). Since the operation of the ELMC relies heavily on the integrity of the PSDs 320, the junction temperature of each PSD 320 should be maintained in its safe operating area. To achieve this a careful selection of the amount of silicon and optimization of the thermal path for the power semiconductors was undertaken. The LMM 310 design provides for adequate cooling and incorporates a thermal shut down protective feature for the PSDs 320 via the associated ASICs 330, as described above.

[0035] In another embodiment, the wire bonds in the individual MOSFET transistors are designed to act as a fusible link in series with the transistor. One of the inherent weaknesses in MOSFET transistors is a short circuit that forms between the drain and source when the device fails. In a power switching and protection device this failure mode can be

catastrophic for the protected (e.g., load, wiring, etc.) devices.

Therefore, designing the wire bonds to act as fusible links can mitigate the damage to the protected devices. Applying similar design rules as used in designing a fuse (e.g., I^2t calculated under the safe operating area of the protected wiring), the MOSFET wire bonds can be designed to provide a delayed fuse for the nominal current rating of the SSSD (e.g., a fifteen amp fuse for a ten amp nominal rated device). Those skilled in the art will appreciate that the specific design criteria is dependent on a number of factors such as wire bond material, anticipated ambient and operating temperatures, and the like. Additionally, since MOSFETs are good current sharing devices when connected in parallel, paralleling the fusible links will also apply to the design considerations.

[0036] ELMC packaging can be implemented as in Figure 4. In this particular case the ELMC contains a relay LMM card 405, five AC SSSD LMMs 406 to 410, one power supply card 411, one Electronic Load Contactor Unit (ELCU) card 412, five DC SSSD LMMs 413 to 417 and a gateway card 418. The relay card is built in a similar way as the SSSD LMM. It contains a plurality of 2 pole double throw (PDT) switches for one phase AC or DC applications, 4PDT switches for AC three phase applications and associated relay drivers controlled by the local microcontroller. Associated monitoring circuitry is provided as required. An ELCU card is provided to control a plurality of electro-mechanical contactors outside ELMC. The ELCU card is built similar to the SSSD LMM. The SSSD is used as contactor coil driver. The ASIC monitors the current conducted through contactor's poles and associated monitoring in a similar fashion as described above. The circular connectors 421 on the front of the chassis are the electrical interfaces with the host vehicle. The internal communication, signal conditioning and internal power supplies to the LMMs are handled by a motherboard card 419 on the bottom half of the chassis. All power lines and distribution lines are wired on the other half of the bottom using a backplane 420.

[0037] As previously discussed, each LMM includes an embedded microcontroller to control and monitor a number of the SSSDs. The LMM can work as a stand-alone module communicating with other subsystem processors via a serial data bus or can communicate with the gateway module card via the serial data bus that extends along the motherboard 419. Those skilled in the art will appreciate that the individual LMM system architecture is designed to accommodate the capability of making local decisions based on a limited number of inputs available.

[0038] The foregoing merely illustrates the principles of the invention. It will be appreciated that those skilled in the art will be able to devise various arrangements, which, although not explicitly described or shown herein, embody the spirit and scope of the present invention. For example, each component described can be used as a complete unit (e.g., LRU) or as a module (e.g., a line replaceable module LRM). In addition, the ASIC, combined with the PSD and associated electronics can be packaged in hybrid case to provide a single solid state power controller function. Therefore, the scope of the invention is not limited by the foregoing description but is defined solely by the appended claims.